

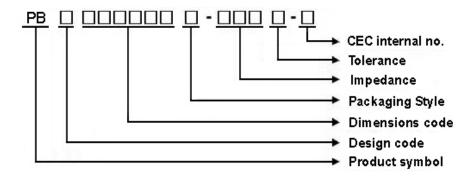
ISO9001 & ISO14001 & TS16949 CHILISIN ELECTRONICS CORP.

Lead-Free & RoHs Compliance!!

SPECIFICATION FOR APPROVAL

CUSTOMER:			
CUSTOMER P/N:			
OUR DWG No:			
QUANTITY:	0 Pc	cs. DATE:	2013/05/24
ITEM:		PBY201209T	-221Y-N
		FICATION PTED BY:	
COMPONENT ENGINEER			
ELECTRICAL ENGINEER			
MECHANICAL ENGINEER			
APPROVED			
REJECTED			
奇力新電子股份有限公司 CHILISIN ELECTRONICS COP NO.29,LANE 301,TEHHSIN RO HSINCHU,TAIWAN,303, REPUBLIC OF CHINA TEL: (03) 599-2646 FAX: (03) 599-9176 E-mail: Sales@chilisin.com.tw http://www.chilisin.com.tw 台北營業處	RP. DAD,HUKOU,		Dongguan) Co., Ltd. Yuliangwei Administration Area, uan City, Guangdong,China -0251~3 3-0232 n.com.tw
Taipei Office 1F., No.2, Aly. 1, Ln. 235, Baod Xindian Dist., New Taipei City 2 TEL:+886-2-6629-5588~9 FAX:+886-2-6629-0088 E-mail:Sales@chilisin.com.tw	231, Taiwan	Chilisin Electronics (Suzhou) Co., Ltd. Rd., Suzhou New District, 350 2356
DRAWN BY 邱郁茹 maggie.chiu		CKED BY 玲 annie	APPROVED BY 詹嘉皓 allen.chan
NI HENH THE SECTION OF	/G////	. 10 00111110	/ 471-1 411-1-1-1-1-1

- 1 Scope: This specification applies to MULTILAYER FERRITE CHIP BEADS
- 2 Part Numbering: Product Identification



3 Rating:

Operating Temperature: $-5.5 \,^{\circ}\text{C} \sim 1.2.5 \,^{\circ}\text{C}$ (Including self - temperature rise)

Storage Temperature: $-55\% \sim 125\%$ (after PCB)

 $-\,5\,\text{°C}\,{\sim}\,4\,\,0\,\text{°C}$,Humidity $\,4\,\,0\,\%\,{\sim}\,7\,\,0\,\%$ (before PCB)

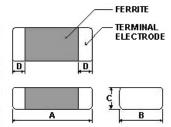
4 Marking:

No Marking

5 Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°ℂ)	20±2 ℃
Humidity	Ordinary Humidity(25 to 85% RH)	60 to 70 % RH

6 Configuration and Dimensions:

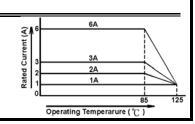


Dimensions in mm			
TYPE	PB201209		
Α	2.00±0.20		
В	1.25±0.20		
С	0.90 <u>+</u> 0.20		
D	0.50±0.30		

7 ELECTRICAL CHARACTERISTICS :

Part No.	Impedance (Ω)	Test Freq.	RDC (Ω)Max.	Rated Current (mA)Max.
PBY201209T-100□-N	10	100 MHz,200 mV	0.01	6000
PBY201209T-170□-N	17	100 MHz,200 mV	0.02	5000
PBY201209T-300□-N	30	100 MHz,200 mV	0.015	4000
PBY201209T-500□-N	50	100 MHz,200 mV	0.025	3000
PBY201209T-600□-N	60	100 MHz,200 mV	0.03	3000
PBY201209T-800□-N	80	100 MHz,200 mV	0.04	3000
PBY201209T-121□-N	120	100 MHz,200 mV	0.04	3000
PBY201209T-221 ₋ N	220	100 MHz,200 mV	0.08	2000
PBY201209T-301□-N	300	100 MHz,200 mV	0.08	2000
PBY201209T-471□-N	470	100 MHz,200 mV	0.1	2000
PBY201209T-601□-N	600	100 MHz,200 mV	0.1	2000
PBY201209T-751□-N	750	100 MHz,200 mV	0.12	1500
PBY201209T-102□-N	1000	100 MHz,200 mV	0.12	1500
PBY201209T-152□-N	1500	100 MHz,200 mV	0.3	1000

NOTE:
--tolerance Y=±25% / T=±30% / 050Y=5±2Ω



^{1.}Operating temperature range $-~5~5~\% \sim 1~2~5~\%$ (Including self - temperature rise)

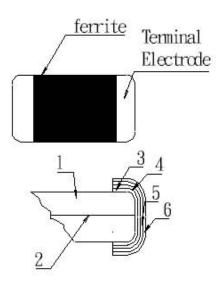
^{3.}As for PB/UPB type. Rated Current is derated as left figure depending on the operating temprature.

[&]quot;-N" FOR COMPLETELY LEAD FREE TYPE(INCLUDING FERRITE BODY & SOLDER)



8 PBY201209T Series

8.1 Construction:



8.2 Material List:

NO	PART	MATERIAL
1	Ferrite Substance	NiO-CuO-ZnO-Ferrite
2	Silver electrode	Ag
3	Silver electrode	Ag
4	Cu plating	Cu
5	Ni plating	Ni
6	Sn plating	Sn



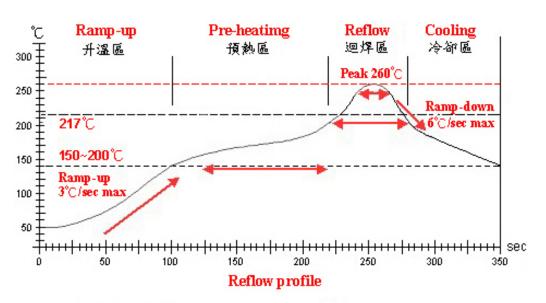
9 Reliability Of Ferrite Multilayer Chip Bead 1-1.Mechanical Performance

No	ltem	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right	Test device shall be soldered on the substrate
		conditions must not damage	Substrate Dimension: 100x40x1.6mm
		the terminal electrode and the	Deflection: 2.0mm
		ferrite	Keeping Time: 30sec
			*For 100505, substrate dimension is 100x40x0.8mm
1-1-2	Vibration		Test device shall be soldered on the substrate
			Oscillation Frequency: 10 to 55 to 10Hz for 1min
			Amplitude: 1.5mm
			Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage	Pre-heating: 150℃, 1min
	-	More than 75% of the terminal	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		electrode should be covered	Solder Temperature: 260±5°C
		with solder.	Immersion Time: 10±1sec
		Impedance : within ±30% of	
		initial value	
1-1-4	Solder ability	The electrodes shall be at	Pre-heating: 150℃, 1min
		least 95% covered with new	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		solder coating	Solder Temperature: 245±5°C (Pb-Free)
			Immersion Time: 4±1sec
1-1-5	Terminal Strength Test	No split termination	Test device shall be soldered on the substrate,
		Chip	then apply a force in the direction of the arrow.
		F	Force : 5N
			Keeping Time: 10±1sec
		Mounting Pad	

1-2.Environmental Performance

No	Item	Specification		Test Method	
1-2-1	Temperature Cycle	Appearance: No damage	One cycle:		
		Impedance: within±30% of	Step	Temperature (°ℂ)	Time (min)
		initial value	1	-55±3	30
			2	25±2	3
			3	125±3	30
			4	25±2	3
			Total: 100c	cycles	
			Measured	after exposure in the room con	dition for 24hrs
1-2-2	Humidity Resistance		Temperature: 40±2°C		
			Relative Hu	umidity: 90 ~ 95% / Time: 1000)hrs
			Measured	after exposure in the room con	dition for 24hrs
1-2-3	High		Temperatu	re: 125±3℃ / Relative Humidit	y: 0%
	Temperature Resistance		Applied Cu	rrent: Rated Current /Time: 10	00hrs
			Measured	after exposure in the room con	dition for 24hrs
1-2-4	Low		Temperatu	re: -55±3°C	
	Temperature Resistance		Relative Hu	umidity: 0% / Time: 1000hrs	
			Measured	after exposure in the room con	dition for 24hrs





Lead-Free(LF) 標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heatimg	迴焊區 Reflow	Peak Temp	冷部區 Cooling
溫度範圍 Temp.scope	R.T. ~150°C	150°C ~ 200°C	217℃	260±5°C	Peak Temp. ~ 150°C
標準時間 Time spec.	_	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	_
實際時間 Time result	7 <u>2</u>	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	_

NOTE:

- 1. Re-flow possible times: within 2 times
- 2. Nitrogen adopted is recommended while in re-flow



11 PACKAGING

11.1 Packaging -Cover tape

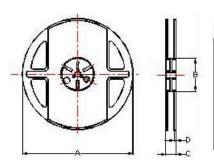
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



11.2 Packaging Quantity

TYPE	BULK	PCS/REEL
PB060303	*	15000
PB100505	*	10000
PB160808	*	4000
PB201209	1	4000

11.3 Reel Dimensions

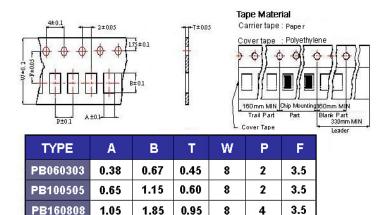


TYPE	Α	В	С	D
PB060303	178	60	12	1.5
PB100505	178	60	12	1.5
PB160808	178	60	12	1.5
PB201209	178	60	12	1.5



11 PACKAGING

11.4 Tape Dimensions in mm



0.97

4

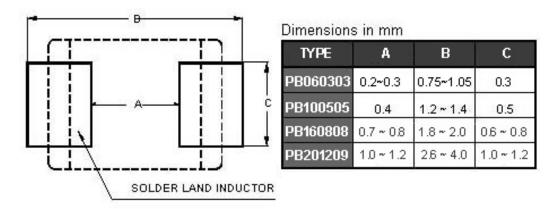
3.5

12 Recommended Pattern

PB201209

1.50

2.30



13 Note:

- 1. Please make sure that your product is has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose, under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)